TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM575440

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT OF THE ENTIRE INTEREST AND THE GOODWILL

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
RAVE N.P., INC.		04/02/2019	Corporation: DELAWARE

RECEIVING PARTY DATA

Name:	Bruker Nano, Inc.
Street Address:	430 S. Congress Avenue, Suite 7
Internal Address:	RAVE Mask Repair Business Unit
City:	Delray Beach
State/Country:	FLORIDA
Postal Code:	33445
Entity Type:	Corporation: ARIZONA

PROPERTY NUMBERS Total: 1

Property Type	Number	Word Mark
Registration Number:	3786068	NANOSNOW

CORRESPONDENCE DATA

Fax Number: 2028611783

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 202861500
Email: bhipdocket@bakerlaw.com
Correspondent Name: Mark H. Tidman
Address Line 1: 1050 Connecticut Avenue, NW
Address Line 2: Washington Square, Suite 1100
Address Line 4: Washington, D.C. 20036-5403

CH $40.00 3786068

ATTORNEY DOCKET NUMBER:	043031.020017
NAME OF SUBMITTER:	Mark H. Tidman
SIGNATURE:	/Mark H. Tidman/
DATE SIGNED:	05/08/2020

Total Attachments: 12
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INTELLECTUAL PROPERTY ASSIGNMENT

This Intellectual Property Assignment (this "Assignment") is made as of April 2, 2019, by and among RAVE LLC, a California limited liability company (the "***Company***"), RAVE N.P., Inc., a Delaware corporation and wholly-owned subsidiary of the Company ("***RNP***"), and RAVE DIAMOND TECHNOLOGIES INC., a Delaware corporation and wholly-owned subsidiary of the Company ("***RDT***," and collectively with the Company and RNP, the "***Assignors***") as assignors, and BRUKER NANO, INC., an Arizona corporation (the "***Assignee***"), as assignee.

RECITALS

A. The Assignors and Assignee, together with the holders of membership interests in the Company, have entered into that certain Asset Purchase Agreement dated as of March 25, 2019 (the "***Purchase Agreement***"), pursuant to the terms of which Assignors agreed to assign the Acquired Intellectual Property to Assignee, which includes, without limitation, the Intellectual Property set forth on **Exhibit A** attached hereto (collectively the "***IP***");

B. Capitalized terms not otherwise defined herein shall have the meanings ascribed to them in the Purchase Agreement; and

C. Pursuant to the terms of the Purchase Agreement, the Assignors and Assignee desire to enter into this Assignment.

AGREEMENT

NOW, THEREFORE, in consideration of the foregoing recitals and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the parties agree as follows:

1. Assignors hereby sell, assign, transfer, convey, and deliver to Assignee their entire right, title and interest in and to the IP, together with all rights, licenses and other agreements, if any, heretofore made by Assignors in respect of, or relating to, the IP, all goodwill associated therewith, all common law rights therein, and all income, royalties, rights to prepare derivative works, fees and payments, if any, now or hereafter due or payable in respect to the IP, including any rights to file an action and recover damages by reason of past infringement, misappropriation or other unauthorized use of the IP, with a right to sue for, and collect the same for its own use and behalf, and for the use and behalf of its successors, assigns, or other legal representatives.

2. Assignee hereby accepts Assignors' assignment and transfer of the IP.

3. Assignors shall execute, acknowledge and deliver to Assignee all documents, instruments and agreements as may be necessary to make a record with any governmental authority (both foreign and domestic) or third parties of this Assignment and Assignee's ownership of all right, title and interest in, to and under the IP.

4. The execution and delivery of this Assignment shall not, in any way, affect, limit, supersede, modify, replace, amend, change, rescind, waive or exceed the rights and obligations of Assignors and Assignee under, or enlarge, restrict or otherwise modify the terms of the Purchase

Agreement, including the warranties, covenants, agreements, conditions, representations or, in general any of the rights and remedies, and any of the obligations and indemnifications of any party set forth in the Purchase Agreement. In the event of any conflict or inconsistency between the terms of the Purchase Agreement and the terms hereof, the terms of the Purchase Agreement shall govern.

5. Should any term or provision of this Assignment be held to any extent unenforceable, invalid, or prohibited under law, then such provision shall be deemed restated to reflect the original intention of the parties as nearly as possible in accordance with applicable law and the remainder of this Assignment. The application of such term or provision to persons, property, or circumstances other than those as to which it is invalid, unenforceable, or prohibited, shall not be affected by such invalidity, unenforceability, or prohibition, and each term and provision of this Assignment shall be valid and enforceable to the fullest extent permitted by law. This Assignment may not be amended except by execution and delivery of an instrument in writing signed by officers of Assignors and Assignee on behalf of Assignors and Assignee.

6. This Assignment and all of the provisions in this Assignment shall be binding upon and inure to the benefit of the successors in interest and assigns of the parties.

7. This Assignment shall be governed by, and construed and interpreted in accordance with the laws of the State of California applicable to agreements made and to be performed entirely within such state, but excluding the conflicts of laws principles thereof.

8. Subject to Section 4 above, this Assignment constitutes the complete and exclusive statement of the agreement between the parties with respect to the subject matter of this Assignment, and this Assignment supersedes any prior oral or written communications, proposals, representations, and agreements. This Assignment and the obligations hereunder are not intended to confer any rights or remedies to any third party and are not intended to operate, in anyway, as an agreement for the benefit of any third party.

9. This Assignment may be executed in counterparts, each of which shall be deemed an original, but all of which together shall constitute one and the same instrument. An executed counterpart of this Assignment transmitted and received by facsimile or PDF shall be deemed for all purposes to be an original, executed counterpart hereof.

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IN WITNESS WHEREOF, the Assignors and Assignee have executed this Assignment as of the day and year first above written.

ASSIGNORS:

RAVE LLC

By: _____
Name: Barry Hopkins
Title: PRESIDENT & CEO

RAVE N.P., INC.

By: _____
Name: Barry Hopkins
Title: PRESIDENT & CEO

RAVE DIAMOND TECHNOLOGIES INC.

By: _____
Name: Barry Hopkins
Title: PRESIDENT & CEO

ASSIGNEE:

BRUKER NANO, INC.

By: _____
Name: Mark R. Munch, Ph.D.
Title: Bruker Nano Group President

IN WITNESS WHEREOF, the Assignors and Assignee have executed this Assignment as of the day and year first above written.

ASSIGNORS:

RAVE LLC

By: _____
Name: _____
Title: _____

RAVE N.P., INC.

By: _____
Name: _____
Title: _____

RAVE DIAMOND TECHNOLOGIES INC.

By: _____
Name: _____
Title: _____

ASSIGNEE:

BRUKER NANO, INC.

By: _____
Name: Mark R. Munch, Ph.D.
Title: Bruker Nano Group President

Exhibit A

See Attached.

Patents and Patent Applications - RAVE LLC		44 active, 34 pending				
Matter	*Name*	*Application*	*Filed*	*Issued*	*Patent*	*Status*
310US/2020	Improved Scan Data Collection (Scan Data)	10/274,669	10/18/02	05/30/06	7,053,369	Active
320US/2040	Improved Scan Data Collection (Scan Data 2)	11/378,583	03/17/06	06/16/09	7,547,882	Active
1121US	Apparatus & Method for Direct Surface Cleaning (Direct)	12/188,564	08/08/08	05/22/12	8,182,609	Active
1122US	Wafer Fabrication Process (Direct Cont - Process)	13/475,997	05/20/12	10/22/13	8,562,749	Active
1141US	Apparatus & Method for Indirect Surface Cleaning (Indirect)	12/055,178	03/25/08	08/09/11	7,993,464	Active
1143A	Apparatus & Method for Indirect Surface Cleaning (1143 Appeal)	12/277,106	11/24/08	10/23/12	8,293,019	Active
1147EP	Apparatus & Method for Indirect Surface Cleaning (EU Indirect)	8796835.0	07/30/08	N/A	see matters 2051-4	Allowed
1148JP	Apparatus & Method for Indirect Surface Cleaning (JP Indirect)	2010-520148	07/30/08	01/11/13	5174910	Active
1150SG	Apparatus & Method for Indirect Surface Cleaning (SG Indirect)	201000882.9	07/30/08	12/14/12	159095	Active
1152KR	Apparatus & Method for Modifying Optical Material Prop. (KR Phase)	10-2010-7005271	08/11/08	02/13/14	10-1365315	Active
1153JP	Apparatus & Method for Modifying Optical Material Prop. (JP Phase)	2010-519997	08/11/08	09/11/13	5,358,572	Active
1154US	Apparatus & Method for Indirect Surface Cleaning (Indirect Cont - Lifetime)	13/657,847	10/22/12	12/24/13	8,613,803	Active
1155US	Apparatus & Method for Indirect Surface Cleaning (Indirect Cont - Wafer)	14/077,028	11/11/13	06/03/14	8,741,067	Active
1156US	Apparatus & Method for Indirect Surface Cleaning (Indirect Cont - Broad)	14/294,728	06/03/14	03/24/15	8,986,460	Active
1157US	Apparatus & Method for Indirect Surface Cleaning (Overlay)	14/656,206	03/12/15	03/15/16	9,285,674	Active
1158TW	Apparatus & Method for Indirect Surface Cleaning (TW Overlay)	105106919	03/07/15			Pending
1161JP	Apparatus and Method for Indirect Surface Cleaning (JP Overlay)	2017-548098	09/21/17			Pending
1162KR	Apparatus and Method for Indirect Surface Cleaning (KR Overlay)	10-2017-7027046	09/21/17			Pending
1163DE	Apparatus and Method for Indirect Surface Cleaning (DE Overlay)	11 2016001162.8	09/12/17			Pending
1170BE	Apparatus & Method for Modifying Optical Material Prop. (BE Phase)	8795203.2	08/11/08	10/07/15	2176708	Active
1171DE	Apparatus & Method for Modifying Optical Material Prop. (DE Phase)	8795203.2	08/11/08	10/07/15	2176708	Active
1172NL	Apparatus & Method for Modifying Optical Material Prop. (NL Phase)	8795203.2	08/11/08	10/07/15	2176708	Active
1180US	Vertical Indent Production Repair (VIPR)	11/898,837	09/17/07	11/09/10	7,829,360	Active
1200US	Debris Removal in High Aspect Structures (Local Clean)	11/898,836	09/17/07	10/16/12	8,287,653	Active
1202TW	Debris Removal in High Aspect Structures (TW Local Clean)	97135684	09/17/08	11/11/14	I460773	Active
1204JP	Debris Removal in High Aspect Structures (JP Local Clean)	2010-525079	09/16/08	10/11/13	5,386,490	Active
1205KR	Debris Removal in High Aspect Structures (KR Local Clean)	10-2010-7008163	09/16/08	08/01/14	10-1428137	Active
1206US	Debris Removal in High Aspect Structures (Local Clean Cont.)	13/652,114	10/15/12	04/15/14	8,696,818	Active
1208US	Debris Removal in High Aspect Structures (LC CIP1-Fibril Structures)	15/011,411	01/29/16			Pending
1209US	Debris Removal in High Aspect Structures (LC CIP2-Analysis Apparatus)	15/160,263	05/20/16			Pending
1210DE	Debris Removal in High Aspect Structures (DE Local Clean)	08832334.0	09/16/08	07/13/16	2198451	Active
1211IT	Debris Removal in High Aspect Structures (IT Local Clean)	08832334.0	09/16/08	07/13/16	2198451	Active
1212IE	Debris Removal in High Aspect Structures (IE Local Clean)	08832334.0	09/16/08	07/13/16	2198451	Active
1213NL	Debris Removal in High Aspect Structures (NL Local Clean)	08832334.0	09/16/08	07/13/16	2198451	Active
1214CH	Debris Removal in High Aspect Structures (Switz. Local Clean)	08832334.0	09/16/08	07/13/16	2198451	Active
1215GB	Debris Removal in High Aspect Structures (GB Local Clean)	08832334.0	09/16/08	07/13/16	2198451	Active
1216EP	Debris Removal in High Aspect Structures (EU LC Div. of 1203EP)	16178942.5	07/12/16	N/A	N/A	Pending
1217PCT	Debris Removal in High Aspect Structures (PCT LC CIP1-Fibril Structures)	PCT/US2017/015062	01/26/17	N/A	N/A	Pending
1218JP	Debris Removal in High Aspect Structures (PCT LC CIP1-Fibril Structures)	2018-539846	07/30/18			Pending
1219KR	Debris Removal in High Aspect Structures (PCT LC CIP1-Fibril Structures)	10-2018-7024622	08/27/18			Pending
1221US	System & Method Improved Crosshatch Nanomach. (Enhanced Cobra)	12/487,227	06/18/09	08/23/11	8,003,283	Active
1222US	Method Fabricating High Aspect Ratio Nanostructure (Enh Cobra Cont)	13/213,532	08/19/11	12/18/12	8,334,084	Active
1223JP	Debris Removal in High Aspect Structures (LC CIP2-Analysis Apparatus)	2017-100801	05/22/17			Pending
1224KR	Debris Removal in High Aspect Structures (LC CIP2-Analysis Apparatus)	10-2017-0061709	05/18/17			Pending
1225TW	Debris Removal in High Aspect Structures (LC CIP2-Analysis Apparatus)	106114454	05/02/17			Pending
1226EP	Debris Removal in High Aspect Structures (LC CIP2-Analysis Apparatus)	17172132.7	05/22/17	N/A	N/A	Pending
1231EU	Debris Removal in High Aspect Structures (PCT LC CIP1-Fibril Structures)	17744875	08/27/18			Pending
1283US	Debris Removal in High Aspect Structures (LC divisional from 1209)	TBD				Pending
1284US	Debris Removal in High Aspect Structures (2nd LC divisional from 1209)	TBD				Pending
2050US	Apparatus & Method for Indirect Surface Cleaning (Indirect Cont)	15/048,774	02/19/16	03/07/17	9,588,420	Active
2051BE	Apparatus & Method for Indirect Surface Cleaning (EU Indirect - from 1147)	8796835.0	05/01/17	09/18/18	2178655	Active
2052DE	Apparatus & Method for Indirect Surface Cleaning (EU Indirect - from 1147)	8796835.0	05/01/17	09/18/18	2178655	Active
2053UNIK	Apparatus & Method for Indirect Surface Cleaning (EU Indirect - from 1147)	8796835.0	05/01/17	09/18/18	2178655	Active
2054NL	Apparatus & Method for Indirect Surface Cleaning (EU Indirect - from 1147)	8796835.0	05/01/17	09/18/18	2178655	Active
2060US	App&Method Nondestructive Detect & ID Surface Cont.(RZ Analysis)	15/400,143	1/6/2017			Pending
2061JP	Apparatus and Method for Contamination Identification (RZ Analysis-JP)	2018-000960	1/9/2018			Pending
2062KR	Apparatus and Method for Contamination Identification (RZ Analysis-KR)	10-2018-0000738	1/3/2018			Pending
2063TW	Apparatus and Method for Contamination Identification (RZ Analysis-TW)	107100468	1/5/2018			Pending
2064UK	Apparatus and Method for Contamination Identification (RZ Analysis-UK)	1800199	1/5/2018			Pending
2065DE	Apparatus and Method for Contamination Identification (RZ Analysis-DE)	10 2018 200 118.9	1/5/2018			Pending
2070US	Debris Removal in High Aspect Structures (LC CIP3-Analysis Method)	15/160,302	05/20/16		TBD	Allowed
2071JP	Debris Removal in High Aspect Structures (LC CIP3-Analysis Method)	2017-100802	05/22/17			Pending
2072KR	Debris Removal in High Aspect Structures (LC CIP3-Analysis Method)	10-2017-0062373	05/19/17			Pending
2073TW	Debris Removal in High Aspect Structures (LC CIP3-Analysis Method)	106115392	05/10/17			Pending
2074EP	Debris Removal in High Aspect Structures (LC CIP3-Analysis Method)	17172136.8	05/22/17	N/A	N/A	Pending
2080US	Method & Apparatus for Pellicle Removal (LN2 aka CPR)	15/190,793	06/23/16	05/01/18	9,958,771	Active
2081JP	Method & Apparatus for Pellicle Removal (LN2)	2016-168911	8/31/16			Pending
2082KR	Method & Apparatus for Pellicle Removal (LN2)	10-2016-0124071	9/27/16			Pending
2083TW	Method & Apparatus for Pellicle Removal (LN2)	105128562	09/05/16			Pending
2084EP	Method & Apparatus for Pellicle Removal (LN2)	16181371.2	07/27/16	N/A	See matters 2090-6	Allowed
2085US	Method and Apparatus for Pellicle Removal (LN2 divisional of 2080)	15/960,733	04/24/18			Pending
2087JP	Method & Apparatus for Pellicle Removal (LN2 - Divisional from 2081)	TBD				Pending
2088KR	Method & Apparatus for Pellicle Removal (LN2 - Divisional from 2082)	10-2018-0124452	10/18/18			Pending
2089TW	Method & Apparatus for Pellicle Removal (LN2 - Divisional from 2083)	TBD				Pending
2090BE	Method & Apparatus for Pellicle Removal (LN2) (nat'l phase of 2084)	16181371.2	07/27/16	03/20/19	3,260,916	Active
2091DE	Method & Apparatus for Pellicle Removal (LN2) (nat'l phase of 2084)	16181371.2	07/27/16	03/20/19	3,260,916	Active
2092FR	Method & Apparatus for Pellicle Removal (LN2) (nat'l phase of 2084)	16181371.2	07/27/16	03/20/19	3,260,916	Active
2093IE	Method & Apparatus for Pellicle Removal (LN2) (nat'l phase of 2084)	16181371.2	07/27/16	03/20/19	3,260,916	Active
2094IT	Method & Apparatus for Pellicle Removal (LN2) (nat'l phase of 2084)	16181371.2	07/27/16	03/20/19	3,260,916	Active
2095NL	Method & Apparatus for Pellicle Removal (LN2) (nat'l phase of 2084)	16181371.2	07/27/16	03/20/19	3,260,916	Active
2096UN	Method & Apparatus for Pellicle Removal (LN2) (nat'l phase of 2084)	16181371.2	07/27/16	03/20/19	3,260,916	Active

	RAVE NP Patents and Applications				6 Pending	37 Allowed/Active
Matter	*Name*	*Country*	*App*	*Filed*	*Patent*	*Status*
21501	Fluid Injection Assembly for Nozzles	U.S.	12/808,750	06/17/10	**8,568,018**	Issued 10/29/13
21503	Fluid Injection Assembly for Nozzles	Taiwan	097149944	12/19/08	**I466729**	Issued 1/1/15
21504	Fluid Injection Assembly for Nozzles	KR	10-2010-7016291	07/20/10	**1506654**	Issued 3/27/15
21540	CO2 Nozzles	U.S.	12/556643	09/10/09	**8,454,409**	Issued 6/4/13
21542	CO2 Nozzles	TW	99130241	10/01/10	**I425556**	Issued 2/1/14
21543	CO2 Nozzles	KR	10-2012-7009277	09/07/10	**10-1792288**	Issued 12/17
21550	CO2 Nozzles	US	13/886,594	05/03/13	**8,801,504**	Issued 8/12/14
21580	Method for selective metal film layer removal using CO jet spray	Canada	2422062	09/12/01	**2,422,062**	Issued 3/18/11
21822	Fluid assisted cryogenic cleaning	Singapore	200405615-6		**106923**	Issued 10/31/06
21823	Fluid assisted cryogenic cleaning	Taiwan	92113360		**I278927**	Issued 4/11/07
21842	Post-CMP cleaning of . . .wafer surfaces using comb. of aqueous & C	China	03819420.1		**100377836C**	Issued 4/2/08
21843	Post-CMP cleaning of . . .wafer surfaces using comb. of aqueous & C	Japan	2003-127199		**3786651**	Issued 3/31/06
21844	Post-CMP cleaning of . . .wafer surfaces using comb. of aqueous & C	Singapore	200500689-5		**110342**	Issued 1/31/07
21845	Post-CMP cleaning of . . .wafer surfaces using comb. of aqueous & C	Taiwan	92113357		**I249783**	Issued 2/21/06
21861	Liquid-assisted cryogenic cleaning	U.S.	10/324,221	12/19/02	**6,852,173**	Issued 2/8/05
21862	Liquid-assisted cryogenic cleaning	U.S.	10/886,251	07/07/04	**7,056,391**	Issued 6/6/06
21881	Vapor-assisted cryogenic cleaning	U.S.	10/403,147	03/31/03	**6,949,145**	Issued 9/27/05
21900	Method for selective metal film layer removal using CO jet spray	U.S.	09/660,354	09/12/00	**6,500,758**	Issued 12/31/02
21902	Method for selective metal film layer removal using CO jet spray	China	01815460.3		**1815460.3**	Issued 4/25/07
21903	Method for selective metal film layer removal using CO jet spray	Japan	2002-527554		**4009533**	Issued 9/7/07
21904	Method for selective metal film layer removal using CO jet spray	Taiwan	90122519		**172753**	Issued 6/25/03
21905	Method for selective metal film layer removal using CO jet spray	Singapore	200301140-0		**95341**	Issued 10/31/05
21906	Method for selective metal film layer removal using CO jet spray	EP	01970888.2	09/21/01	**1317767**	Issued
21908	Method for selective metal film layer removal using CO jet spray	Germany	01970888.2		**EP1317767**	Issued 2/21/07
21909	Method for selective metal film layer removal using CO jet spray	France	01970888.2		**EP1317767**	Issued 2/21/07
21910	Method for selective metal film layer removal using CO jet spray	UK	01970888.2		**EP1317767**	Issued 2/21/07
21911	Method for selective metal film layer removal using CO jet spray	Ireland	01970888.2		**EP1317767**	Issued 2/21/07
21912	Method for selective metal film layer removal using CO jet spray	Italy	01970888.2		**EP1317767**	Issued 2/21/07
21913	Method for selective metal film layer removal using CO jet spray	Netherlands	01970888.2		**EP1317767**	Issued 2/21/07
22060	Apparatus and method for analysis of impurities in liquid CO2	U.S.	09/411,396	10/04/99	**6,276,169**	Issued 8/21/01
22061	Apparatus for analysis of impurities in liquid CO2	U.S.	09/886,098	06/22/01	**6,405,560**	Issued 6/18/01
22201	Contamination Removal App.&Method (Plasma Cont/) (Plasma2)	US	13/897,552	05/20/13	**10,245,623**	**Issued 4/2/19**
22203	Contamination Removal App.&Method (Plasma Cont/) (Plasma2)	TW	102117589	05/17/13	**I632002**	Issued 8/11/18
22204	Contamination Removal App.&Method (Plasma Cont/) (Plasma2)	JP	2015-512839	01/07/15	**6,336,939**	Issued 5/11/18
22205	Contamination Removal App.&Method (Plasma Cont/) (Plasma2)	KR	10-2014-1035484	12/17/14		Pending
22206	Contamination Removal App.&Method (Plasma Cont/) (Plasma2)	Germany	11 2013 002 561.2	12/18/14		Pending
22207	Contamination Removal App.& Method (Plasma Divisional) (Plasma2	US	15/453,283	03/08/17		Pending
22208	Contamination Removal App.& Method (Plasma CIP) (Plasma3)	US	TBD	TBD		TBD
22221	Smart Valve	US	14/189,337	02/25/14	**9,822,903**	Issued 11/21/17
22222	Smart Valve (PCT)	PCT	PCT/US2014/059213	02/24/14	N/A	PCT
22223	Smart Valve (JP)	JP	2015-559037	01/11/16	6,415,457	Issued 10/12/18
22224	Smart Valve (KR)	KR	10-2015-7026522	01/11/16		Pending
22225	Smart Valve (EPO)	EP	14753929.0	01/11/16	N/A	Pending
22100	System and Method for Scanning Boom Microscope	US	11/336,390	01/01/06	**7,564,625**	Issued 7/21/09

RAVE LLC Trademarks

Matter	Country	Trademark	Status	Reg. Number	Class
2	US	ENABLING TOMORROW'S TECHNOLOGY TODAY	Registered	3311766	09 Int., 37 Int.
3	US	NANOBITS	Registered	3378532	07 Int.
4	US	MERLIN	Registered	3777729	09 Int.
6	KR	MERLIN	Registered	40-886103	09 Int.
7	JP	MERLIN	Registered	5,521,074	09 Int.
8	US	RHAZER	Registered	3903813	09 Int.
9	US	BITCLEAN	Registered	3940192	09 Int.
31	US	NM-VI	Registered	87519226	9 Int.
20002	US	FP-III	Registered	87519233	9 Int.
20003	US	Rhazer-III	Registered	87519237	9 Int.
35	KR	NANO-VI	Registered	1368989	9 Int.
36	TW	FP-III	Applied		9 Int.
39	KR	FP-III	Registered	8-5-2019-001331834	9 Int.
40	TW	Rhazer-III	Registered	1928139	9 Int.
43	KR	RHAZER III	Registered	8-5-2019-001344670	9 Int.
44	TW	NM-VI	Registered	1930925	9 Int.
47	KR	NM-VI	Registered	8-5-2019-001097631	9 Int.
48	DE, JP	NANO-VI	Registered	1368989	9 Int.
49	DE, JP	NM-VI	Registered	1368990	9 Int.
50	DE, JP	FP-III	Registered	1368568	9 Int.
51	DE, JP	RHAZER III	Registered	1368569	9 Int.

RAVE NP Trademarks

Matter	Country	Trademark	Status	Reg. Number	Reg. Date	Class
20000	US	SNOWSTRIP	Registered	3,923,748	02/22/11	3
20004	US	ECO-SNOW	Registered	2,429,388	02/20/01	7, 9
20005	JP	ECO-SNOW	Registered	4,902,470		
20006	CH	ECO-SNOW	Registered	6,794,550		
20008	US	WAFERCLEAN	Registered	3,434,792	05/27/08	7,9
20010	US	MaskClean	Registered	3,316,126	10/23/07	1
	JP	WAFERCLEAN	Registered	4,904,954		
20012	US	VersaClean	Registered	3,316,127	10/23/07	1
20013	JP	VersaClean	Registered	4,902,471		1
	JP	MaskClean	Registered	4,902,472		
20014	US	PrecisionClean	Registered	3,070,328	03/21/06	7
20015	US	PrecisionClean	Registered	3,316,697	10/23/07	1
20016	JP	PrecisionClean	Registered	5,090,000		17
20017	US	NANOSNOW	Registered	3,786,068	05/04/10	7

RNP Copyrights

Country	Work	Status	Reg. Number	Reg. Date	Recorded Owner
US	Maskclean 150 Software	Registered	TX0007197625	2/17/2010	RAVE, N.P., Inc.
US	Waferclean 1600 Software	Registered	TX0005954215	2/27/2004	RAVE, N.P., Inc.
US	Waferclean 1600 Software	Registered	TX0005903905	3/28/2004	RAVE, N.P., Inc.

Assumed Name / Fictitious Name Permits:

Eco-Snow Systems	California
RAVE Repair & Cleaning LLC	Texas
Rave Service Organization	Florida
Micro Star Technologies	Texas; Florida
Advanced Micro Patterning	Florida

Domains:

www.ravenano.com
www.ecosnow.com
www.microstartech.com
http://intelligentmp.com/

Intellectual Property Licenses

1. IBM Business Partner Embedded Solution Agreement, by and between Arrow Electronics Inc. and Rave LLC, dated July 23, 2018. Arrow – IBM DB2 software license. Fee based. Notice required for assignment.

2. Development Services Agreement by and between Rave LLC and Chardon Tool & Supply Co., Inc., dated as April 9, 2019. Chardon – Diamond tip development agreement. Fee based. Notice required for assignment.

3. Agreement Concerning Work Related Intellectual Property, by and between Rave and Polytec, dated March 9, 2016. Polytec - Exclusivity agreement. Volume based.

4. Software License Agreement, by and between JNBridge, LLC. JN Bridge – Software license. Fee based. Notice and assignee consent to agreement required for assignment.

5. Qt Commercial Distribution License Agreement version 2.3, by and between Digia USA, Inc. and Rave LLC, dated July 31, 2012. Nokia/Digia – Software license. Fee based. Consent required for assignment.

6. PFAT Software Subscription and License Agreement and Terms and Conditions, by and between Rave LLC and PEER Group Inc., dated September 30, 2011. Peer Group – Software services. Fee based. Consent required for assignment.

7. Qt Extended Support Agreement, dated April 25, 2018, by and between the Qt Company and Rave LLC. QT – Software support agreement. Fee based. Consent required for assignment.

8. Software License Agreement dated August 30, 2018, by and between Syspro Impact Software, Inc. and its independent reseller Lonehill Systems, Inc. and Rave LLC. Syspro - Software license and services. Fee based. Consent required for assignment.

9. Manufacturing Agreement, by and among Rave LLC, General Nanotechnology LLC and Team Nanotec GmbH, dated April 8, 2003. Consent required for assignment, but superseded in part by Settlement Agreement (item 11 below).

10. Standard Exclusive License Agreement with Sublicensing Terms Number LIC16020 by and between the University of South Florida Research Foundation, Inc. and Rave LLC, dated February 1, 2016. USF - University of South Florida patent & know-how license. Royalty and fee bearing. Consent required for assignment.

11. Settlement Agreement, Release, License and Covenant Not to Sue, by and among RAVE LLC, Victor Kley, General Nanotechnology LLC, Terraspan LLC, Metadigm LLC, Sunshell LLC, and Denise Ligenfelter, dated January 19, 2016.

12. Trademark License Agreement by and between Linde LLC and Rave N.P., Inc. dated June 30, 2010. License from RNP to Linde.

13. Patent License Agreement by and between Rave N.P., Inc. and Linde LLC, dated June 30, 2010. License from RNP to Linde.

14. RAVE grants licenses to its customer to use products purchased from RAVE as set forth in customer agreements, including but not limited to the following:

    a. Commercial Equipment Purchase Specifications (CEPS) by and between Advanced Mask Technologies Center GmbH & Co. KG (AMTC) and Eco-Snow Systems a division of Rave N.P., Inc., dated January 19, 2017 (the "AMTC CEPS").
    b. Equipment Agreement #4904IM0091 by and between International Business Machines Corporation and Rave LLC, dated August 20, 2004.
    c. Intel Corporation Purchase Order #4200122955, dated December 29, 2019.
    d. Chartered Purchase Order F8L-256255 and Accompany Terms and Conditions of Purchase by and between Chartered Semiconductor Manufacturing Ltd and Rave, LLC, dated April 8, 2009.

Rave N.P., Inc. provided a Notice in 2018 to USF of potential infringement of Rave N.P., Inc. (AMP) license rights.

The Company's legal department received an internal notice on March 13, 2019 regarding potential infringement of Rave N.P., Inc. patent or know-how rights regarding the sale of nozzles for cryogenic cleaning tools.